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Unit 5 - WEEK 04 Design Practice II

Assignment 04_Design Practice 2

The due date for submitting this assignment has passed.
As per our records you have not submitted this assignment. **Due on 2018-09-26, 23:59 IST.**

1) ..... is considered as the most expensive micromechanical process: ***1 point***

- Etching
- Lift-off technique
- Lithography
- Masking

No, the answer is incorrect.
Score: 0

Accepted Answers:
Lithography

2) Lithography is used for: ***1 point***

- Forming resist layers on the substrate
- Cutting tool
- Forming electric bonds
- None of these

No, the answer is incorrect.
Score: 0

Accepted Answers:
Forming resist layers on the substrate

3) Types of lithography: ***1 point***

- Photolithography
- X-ray lithography

4) Types of photoresist: ***1 point***

- Positive
- Negative
- Positive and Negative
- None of them

No, the answer is incorrect.
Score: 0

Accepted Answers:
Positive and Negative

5) State which of the following statements is/are true ***1 point***

- Positive photoresist softens on exposure to UV light
- Positive photoresist hardens on exposure to UV light
- Negative photoresist softens on exposure to UV light
- Negative photoresist hardens on exposure to UV light

No, the answer is incorrect.
Score: 0

Accepted Answers:
Positive photoresist softens on exposure to UV light
Negative photoresist hardens on exposure to UV light

6) In X-ray lithography, the X-ray absorber is usually: ***1 point***

- Silver
- Gold
- Aluminum
- None of them

No, the answer is incorrect.
Score: 0

Accepted Answers:
Gold

7) ..... is projecting electron beam directing on photoresist of the wafer: ***1 point***

- E-beam lithography
- Light emitting
- Electron beam gun
- Radar beam

No, the answer is incorrect.
Score: 0

Accepted Answers:
E-beam lithography

8) The electron gun is used in lithography because it is.....: ***1 point***

- Inexpensive
- Accurate
- Doesn't require high voltage
- None of them

No, the answer is incorrect.
Score: 0

Accepted Answers:
Accurate

9) …… used for removing desired areas of the photo resist from the substrate: ***1 point***

- LIGA
- Lithography
- Etching
- None of them

No, the answer is incorrect.
Score: 0

Accepted Answers:
Etching

10)Types of etching are.....: ***1 point***

- Wet isotropic
- Wet anisotropic
- Dry
- All of them

No, the answer is incorrect.
Score: 0

Accepted Answers:
All of them

11).....is an Etch stop technique. ***1 point***

- Wet isotropic etching
- Wet anisotropic etching
- Electrochemical etching
- Physical sputter etching

No, the answer is incorrect.
Score: 0

Accepted Answers:
Electrochemical etching

12)……..is the etching through chemical or physical interaction between ions: ***1 point***

- Wet isotropic etching
- Wet anisotropic etching
- Dry etching
- None of these

No, the answer is incorrect.
Score: 0

Accepted Answers:
Dry etching

13)…… is used for metals that are hard to etch: ***1 point***

- Lift-off technique

- Combined physical/chemical etching
- Physical sputter etching
- Chemical plasma etching

No, the answer is incorrect.
Score: 0

Accepted Answers:
Lift-off technique

Previous Page End